

Features

- Low profile package
- Ideal for automated placement
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC



SMC (DO-214AB)

Mechanical Date

- **Case:** JEDEC DO-214AB molded plastic
- **Terminals:** Solder plated, solderable per
JESD22-B102D
- **Polarity:** Laser band denotes cathode end

Major Ratings and Characteristics

$I_{F(AV)}$	5.0A
V_{RRM}	20 V to 200 V
I_{FSM}	150A
V_F	0.50V, 0.55V, 0.70V, 0.85V, 0.95V
$T_j \text{ max.}$	125 °C

Maximum Ratings & Thermal Characteristics

($T_A = 25\text{ °C}$ unless otherwise noted)

Items	Symbol	SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current	$I_{F(AV)}$	5									A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	150									A
Voltage rate of change (rated V_R)	dv/dt	10000									V/ μ s
Thermal resistance from junction to lead ⁽¹⁾	$R_{\theta JL}$	20									°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-65 to +125									°C

Note 1: Mounted on P.C.B. with 0.55 × 0.55" (14 × 14 mm) copper pad areas.

Electrical Characteristics ($T_A = 25\text{ °C}$ unless otherwise noted)

Items	Test conditions		Symbol	SS52	SS53~54	SS55~56	SS58~510	SS515~520	UNIT
Instantaneous forward voltage	$I_F=5.0A^{(2)}$		V_F	0.50	0.55	0.70	0.85	0.95	V
Reverse current	$V_R=V_{DC}$	$T_J=25^{\circ}C$	I_R	0.5					mA
		$T_J=100^{\circ}C$		10.0					

Note 2: Pulse test: 300 μ s pulse width, 1% duty cycle.

Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

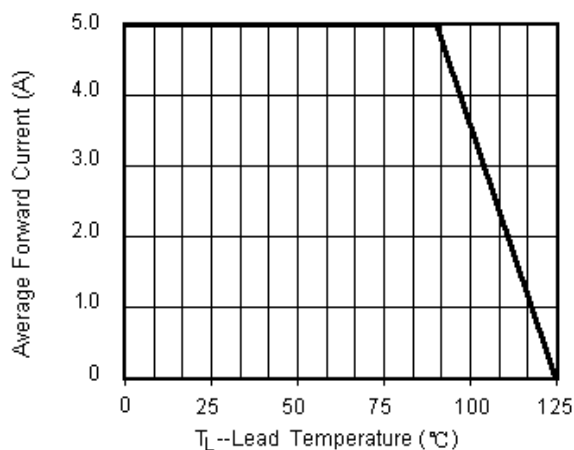


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

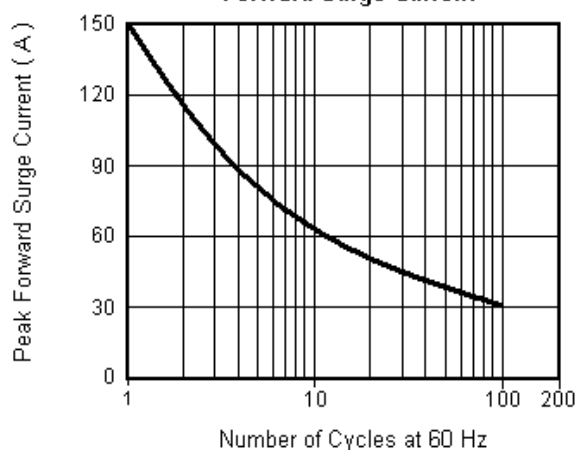


Fig.3 Typical Instantaneous Forward Characteristics

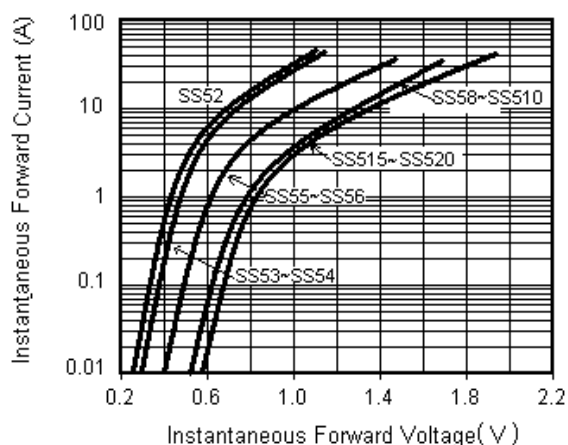
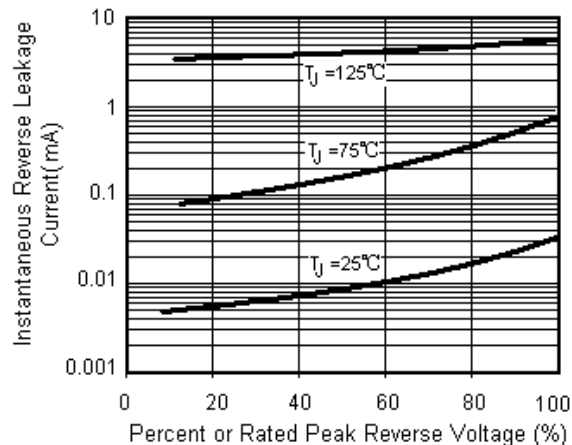
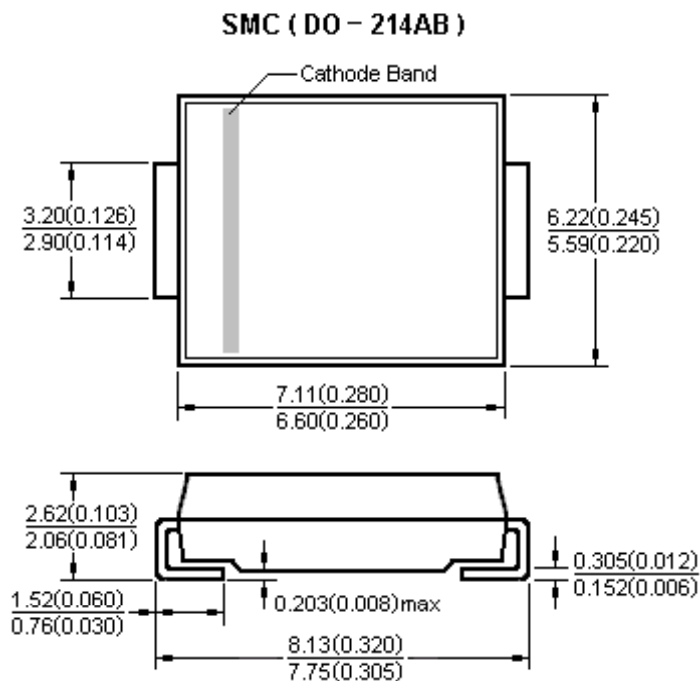


Fig.4 Typical Reverse Leakage Characteristics



Package Outline



Dimensions in millimeters and (inches)

Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.

$I_{F(AV)}$: We recommend that the worst case current be no greater than 80% .

T_J : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a T_J of below 100°C.

- TRR is registered trademark of Zhejiang TRR Microelectronics Inc. Zhejiang TRR Microelectronics Inc reserves the right to make changes to any product in this specification without notice.
- Zhejiang TRR Microelectronics Inc does not assure any liability arising out of the applications or use of any product described in this specification.
- Zhejiang TRR Microelectronics Inc advises customers to obtain the latest version of the device information before placing orders to verify that the required information is current.